

Transport properties of n- and p-type polycrystalline BaSi₂

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Abstract. Electron and hole mobilities versus temperature in semiconducting barium disilicide (BaSi_2) have been systematically studied both experimentally and theoretically. The experiments were performed with undoped 250 nm-thick BaSi_2 polycrystalline films grown by molecular beam epitaxy. The grain size of films ranged from 0.2 to 5 μm with the electron concentration of $5.0 \times 10^{15} \text{ cm}^{-3}$. To investigate the hole mobility, B-doped p - BaSi_2 films with various dopant concentrations were fabricated and studied. The experimental temperature dependence of the electron mobility in the range of 160–300 K was found to have a maximum of $1230 \text{ cm}^2/\text{V}\cdot\text{s}$ at 218 K, while at room temperature (RT) it dropped down to $816 \text{ cm}^2/\text{V}\cdot\text{s}$. We demonstrate that the temperature dependence of the electron mobility cannot be adequately reproduced by involving standard scattering mechanisms. A modified approach accounting for the grained nature of the films has been proposed for the correct description of the mobility behavior. The highest hole mobility in p - BaSi_2 films reaching ~ 80 or $200 \text{ cm}^2/\text{V}\cdot\text{s}$ (for the films grown on (111) or (001) Si substrates, respectively) at RT is about an order or four times of magnitude smaller than that in n - BaSi_2 films. Such a great difference we ascribe to the specific features of electron-phonon and hole-phonon coupling in semiconducting BaSi_2 .

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